

Flexible PCB—Production Capability part.1

Item		(2017) Capability			2018
		Max	Min	Tolerance	
Layers		6Layers	1 Layers		10Layers
Copper Thickness	Outer Layer	2 oz	1/3 oz		1/4 oz
	Inner Layer	1 oz	1/3 oz		1/4 oz
FPC Thickness		0.6mm	0.058mm(2.5mil)	±0.03mm (1.25mil)	
Outline size		200mm*800mm			250mm*800mm
Size	Panel	350mm*420mm	120mm*250mm	±0.15mm (6mil)	500mm*420mm
	Outline to Outline			±0.1mm (4mil)	
	Hole to Outline			±0.1mm (4mil)	
	Pitch to Outline			±0.05mm (2mil)	
Line Width/Space	Outer Layer		0.05mm (2mil)	±0.01mm (0.4mil)	0.04mm (1.6mil)
	Inner Layer		0.05mm (2mil)	±0.01mm (0.4mil)	
Pitch			0.10mm (4mil)	±0.02mm (0.8mil)	
PI Cross Hatching	Cover Finger		0.15mm(6mil)		
	IC to IC		0.10mm(4mil)		0.075mm(3mil)

Flexible PCB—Production Capability part.2

Item		(2017) Capability			2018
		Max	Min	Tolerance	
Hole Size	NPTH	10mm	0.1mm(4mil)	±0.05mm (2mil)	
	PTH	10mm	0.1mm(4mil)	±0.05mm(2mil)	
Laser Drilling	PTH	10mm	0.1mm(4mil)	±0.05mm(2mil)	
	NPTH	10mm	0.1mm(4mil)	±0.05mm(2mil)	
Anuular Ring	Outer Layer		0.10mm(4mil)		0.075mm(3mil)
	Inner Layer		0.10mm(4mil)		0.05mm(2mil)
Inner Space	Min		0.10mm(4mil)		0.075mm(3mil)
	Line to Pad		0.10mm (4mil)		0.075mm(3mil)
	Pad to Pad		0.10mm (4mil)		0.075mm(3mil)
	Line to Line		0.05mm(2mil)		
Solder Resist Bridge			0.05mm(2mil)		
Legend	Line width		0.12mm(5mil)		0.1mm(4mil)
	Height		0.8mm(32mil)		
Copper Plating	Thickness of Hole Wall	36um	8um		72um
	Plating Uniformity			±2um	

Flexible PCB—Production Capability part.3

Item		(2017) Capability			2018
		Max	Min		
Surface Treatment of Finish	Immersion Gold	Au 0.2um(8u “)	0.025um(1u")		
		Ni 8um (320u")	Ni 1.0um(40u")		
	Soft Gold Plated	0.5um(20u")	0.03um (1.5u")		1.0um(40u")
	Hard Gold Plated	0.76um(30u")	0.05um (2u")		
	Immersion Tin	1.2um(48u")	0.8um (32u")		
	Tin Plated	30um(1200u")	6um (240u")		
	O.S.P	0.04um(1.6u")			
Qualified Standard	Aspect	IPC-A-600F			
	Test	IPC-TM-650			